

CED1012-VB Datasheet N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)		
100	0.110 at V _{GS} = 10 V	15		
100	0.115 at V _{GS} = 6 V	15		

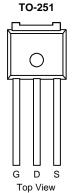
FEATURES

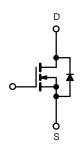
- DT-Trench Power MOSFET
- 175 °C Junction Temperature
- 100 % R_g Tested

APPLICATIONS

• Primary Side Switch







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \text{ °C}$, unless otherwise noted)				
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	100	V
Gate-Source Voltage		V _{GS}	± 20	v
Orational Projection Orace (Terrated Control	T _C = 25 °C		15	
Continuous Drain Current $(T_J = 175 \ ^{\circ}C)^{b}$	T _C = 125 °C	I _D	8.7	
Pulsed Drain Current		I _{DM}	45	А
Continuous Source Current (Diode Conduction)		۱ _S	15	1
Avalanche Current		I _{AR}	15	
Repetitive Avalanche Energy (Duty Cycle \leq 1 %)	L = 0.1 mH	E _{AR}	11.3	mJ
Maximum Power Dissipation	T _C = 25 °C	P _D	61 ^b	W
	T _A = 25 °C	טי	2.7 ^a	vv
Operating Junction and Storage Temperature Range	-	T _J , T _{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
hurstien te Amhiesta	t ≤ 10 s	P	16	20	
Junction-to-Ambient ^a	Steady State	R _{thJA}	45	55	°C/W
Junction-to-Case		R _{thJC}	2	2.4	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. See SOA curve for voltage derating.

$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	0 V
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	0 nA 00 nA 0 μA 0 A Ω
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	0 nA 00 nA 0 μA 0 A Ω
Gate-Body Leakage I_{GSS} $V_{DS} = 0$ V, $V_{GS} = \pm 20$ V ± 1 Zero Gate Voltage Drain Current I_{DSS} $V_{DS} = 100$ V, $V_{GS} = 0$ V $= 20$ $= 20$ On-State Drain Current ^b $I_{D(on)}$ $V_{DS} = 100$ V, $V_{GS} = 0$ V, $T_J = 125$ °C $= 22$ On-State Drain Current ^b $I_{D(on)}$ $V_{DS} = 5$ V, $V_{GS} = 10$ V $= 22$ On-State Drain Current ^b $I_{D(on)}$ $V_{DS} = 5$ V, $V_{GS} = 10$ V $= 15$ Drain-Source On-State Resistance ^b $R_{DS(on)}$ $V_{GS} = 10$ V, $I_D = 15$ A, $T_J = 125$ °C 0.110 $V_{GS} = 10$ V, $I_D = 15$ A, $T_J = 175$ °C 0.230 $V_{GS} = 10$ V, $I_D = 15$ A, $T_J = 175$ °C 0.230 $V_{GS} = 10$ V, $I_D = 15$ A, $T_J = 175$ °C 0.230 $V_{GS} = 10$ V, $I_D = 15$ A, $T_J = 175$ °C 0.230 $V_{GS} = 10$ V, $I_D = 15$ A, $T_J = 175$ °C 0.230 $V_{GS} = 6$ V, $I_D = 10$ A 0.115 Forward Transconductance ^b g_{fs} $V_{DS} = 0$ V, $V_{DS} = 25$ V, $f = 1$ MHz 892 Input Capacitance C_{oss} $V_{GS} = 0$ V, $V_{DS} = 25$ V, $f = 1$ MHz 110 Reverse Transfer Capacitance C_{rss}	0 nA 00 nA 0 μA 0 A Ω
Zero Gate Voltage Drain Current I_{DSS} $V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$ I_{DSS} $V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125 ^{\circ}\text{C}$ Z_{SS} On-State Drain Current ^b $I_{D(on)}$ $V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 175 ^{\circ}\text{C}$ Z_{SS}	Δμ 0 Α Ω
Zero Gate Voltage Drain Current I_{DSS} $V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125 ^{\circ}\text{C}$ Image: Constant of the state definition of the	Aμ 0 0 A Ω
$ \begin{array}{ c c c c c } \hline V_{DS} = 100 \ V, \ V_{GS} = 0 \ V, \ T_J = 175 \ ^{\circ}C & 0 & 2 \\ \hline V_{DS} = 100 \ V, \ V_{GS} = 0 \ V, \ T_J = 175 \ ^{\circ}C & 15 & 0 \\ \hline V_{DS} = 5 \ V, \ V_{GS} = 10 \ V & 15 & 0 & 0 \\ \hline V_{GS} = 10 \ V, \ I_D = 15 \ A & 0.110 & 0 \\ \hline V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 125 \ ^{\circ}C & 0.170 & 0 \\ \hline V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 175 \ ^{\circ}C & 0.230 & 0 \\ \hline V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 175 \ ^{\circ}C & 0.230 & 0 \\ \hline V_{GS} = 6 \ V, \ I_D = 10 \ A & 0.115 & 0 \\ \hline V_{GS} = 6 \ V, \ I_D = 10 \ A & 0.115 & 0 \\ \hline Dynamic^a & 0 \\ \hline Dynamic^a & 0 \\ \hline Duput \ Capacitance & C_{iss} & V_{GS} = 0 \ V, \ V_{DS} = 25 \ V, \ f = 1 \ MHz & 110 & 0 \\ \hline Reverse \ Transfer \ Capacitance & C_{rss} & 0 \\ \hline Total \ Gate \ Charge^c & Q_g & 0 \\ \hline \end{array}$	0 A A Ω
$ \begin{array}{c c c c c c c c c c } On-State Drain Current^b & I_{D(on)} & V_{DS} = 5 \ V, \ V_{GS} = 10 \ V & 15 & 16 & 16 & 16 & 16 & 16 & 16 & 16$	Ω
$ \begin{array}{c c c c c c c c c } P_{GS} = 10 \ V, \ I_D = 15 \ A & 0.110 \\ \hline V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 125 \ ^{\circ}C & 0.170 \\ \hline V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 125 \ ^{\circ}C & 0.230 \\ \hline V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 175 \ ^{\circ}C & 0.230 \\ \hline V_{GS} = 6 \ V, \ I_D = 10 \ A & 0.115 \\ \hline V_{GS} = 6 \ V, \ I_D = 10 \ A & 0.115 \\ \hline \end{array} $	Ω
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Forward Transconductanceb g_{fs} $V_{DS} = 15 \text{ V}, I_D = 15 \text{ A}$ 25DynamicaInput Capacitance C_{iss} Output Capacitance C_{oss} VGS = 0 V, VDS = 25 V, f = 1 MHz110Reverse Transfer Capacitance C_{rss} Total Gate Charge ^c Q_g	
DynamicaSolutionSoluti	<u> </u>
$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	5
Output Capacitance C_{oss} $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$ 110Reverse Transfer Capacitance C_{rss} 70Total Gate Charge ^c Q_g 20	
Reverse Transfer Capacitance C _{rss} 70 Total Gate Charge ^c Q _g 20 2	
Reverse Transfer Capacitance C _{rss} 70 Total Gate Charge ^c Q _g 20 2	pF
Gate-Source Charge ^c Q _{gs} V _{DS} = 75 V, V _{GS} = 10 V, I _D = 15 A 5.5	5
	nC
Gate-Drain Charge ^c Q _{gd} 7	
Gate Resistance R _g 1 3	2 Ω
Turn-On Delay Time ^c t _{d(on)} 8 1	2
Rise Time ^c t_r $V_{DD} = 75 V, R_L = 5 \Omega$ 35 5	5
Turn-Off Delay Time ^c $t_{d(off)}$ $I_D \cong 15 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 2.5 \Omega$ 172	5 ns
	5
Source-Drain Diode Ratings and Characteristic ($T_c = 25 \ ^\circ C$)	
Pulsed Current I _{SM}	5 A
Diode Forward Voltage ^b V_{SD} $I_F = 15 \text{ A}, V_{GS} = 0 \text{ V}$ 0.9 1	5 V
Source-Drain Reverse Recovery Time t_{rr} $I_F = 15 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$ 55 8	5 ns

Notes:

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

c. Independent of operating temperature.

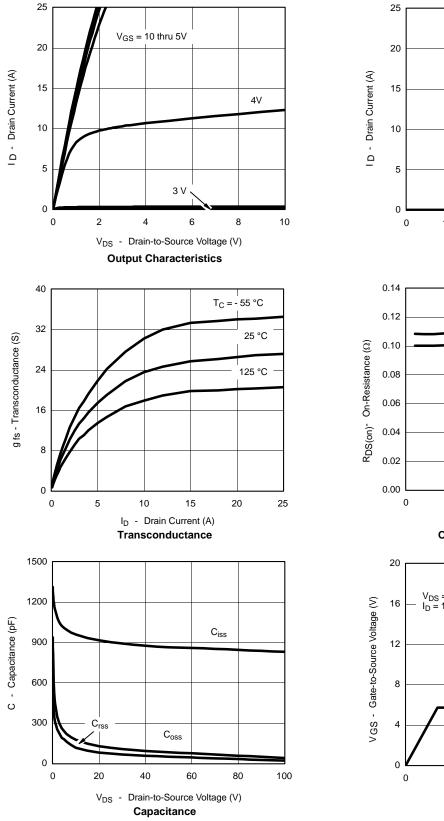
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

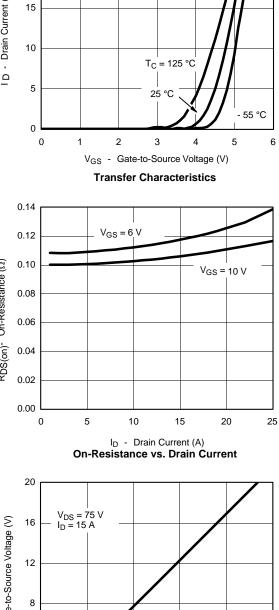
semi

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TYPICAL CHARACTERISTICS (25 °C unless noted)





8

16

Qg - Total Gate Charge (nC)

Gate Charge

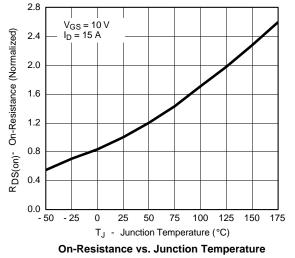
24

32

40



TYPICAL CHARACTERISTICS (25 °C unless noted)



THERMAL RATINGS

2

1

0.1

0.01

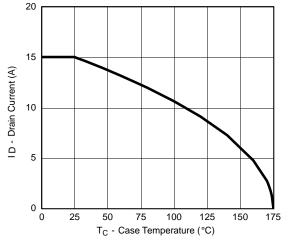
10-4

Normalized Effective Transient Thermal Impedance Duty Cycle = 0.5

0.02

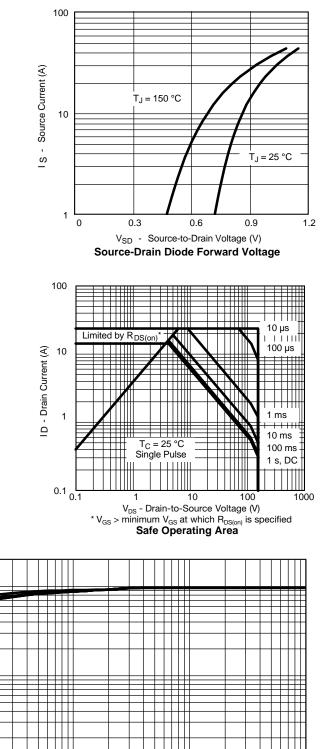
0.05 0.05 Single Pulse

0.2 0.1



Maximum Avalanche Drain Current vs. Case Temperature

10⁻³



1

Square Wave Pulse Duration (sec) Normalized Thermal Transient Impedance, Junction-to-Case

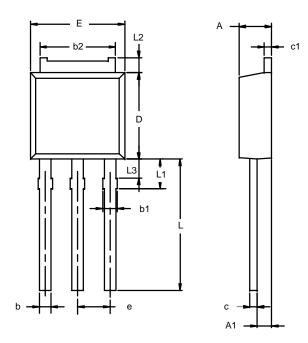
10⁻¹

10-2

10



TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

Min	Max		
	Max	Min	Max
2.21	2.38	0.087	0.094
0.89	1.14	0.035	0.045
0.71	0.89	0.028	0.035
0.76	1.14	0.030	0.045
5.23	5.43	0.206	0.214
0.46	0.58	0.018	0.023
0.46	0.58	0.018	0.023
5.97	6.22	0.235	0.245
6.48	6.73	0.255	0.265
2.28 BSC		0.090 BSC	
8.89	9.53	0.350	0.375
1.91	2.28	0.075	0.090
0.89	1.27	0.035	0.050
1.15	1.52	0.045	0.060
	0.71 0.76 5.23 0.46 0.46 5.97 6.48 2.28 8.89 1.91 0.89 1.15	0.71 0.89 0.76 1.14 5.23 5.43 0.46 0.58 0.46 0.58 5.97 6.22 6.48 6.73 2.28 BSC 8.89 9.53 1.91 2.28 0.89 1.27	0.71 0.89 0.028 0.76 1.14 0.030 5.23 5.43 0.206 0.46 0.58 0.018 0.46 0.58 0.018 5.97 6.22 0.235 6.48 6.73 0.255 2.28 BSC 0.090 8.89 9.53 0.350 1.91 2.28 0.075 0.89 1.27 0.035 1.15 1.52 0.045



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